

Product data sheet

PRODUCENT: AG Termopasty Grzegorz Gąsowski 18-100 Łapy, ul. Harcerska 8, tel./fax (085) 715 79 80

No Clean Soldering Paste

/Sn96,5Ag3Cu0,5/

Description:

■ Paste for soldering of surface-mounted (SMD) components

Advantages:

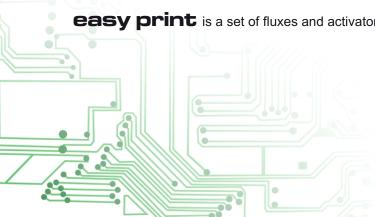
- Resistant to solderballing (mid chip solderballing)
- Good adhesion to components for over 24hrs after application
- Exhibits long stencil life even for 8hrs of continuous printing, prolonged usability (stencil life)
- Low level of colourless, non-corrosive soldering residues (no clean), that are flexible enough to allow penetration of tester needles
- Fine pitch
- Printing with squeegee speed up to 150mm/s

Technical details

Properties	Results	Procedures					
Chemical							
type of solder	Sn96,5Ag3Cu0,5						
classification of flux	REL - 0	J-STD - 004					
paper chromatography test on Clfiz	satisfy (REL - 0)	IPC TM 650					
Physical							
density	≈4,6 g/cm³	IPC-TM 650T					
particle size	25-45 μm	IPC-TM 650T					
tackiness	1,0 G/mm² after 24h	IPC J-STD - 005					
printability	more than 8h						
Electrical							
SIR-IPC	> 2,6*10°Ω, after 7 days	IPC J-STD 004 (85°C, in 85%)					

Syllibus. SIR - Surface Insulation Resistance IPC - J STD 004/005, IPC - TM650 - American standards defining technical requirements for pastes and fluxes

easy print is a set of fluxes and activators that should be considered as non-toxic.



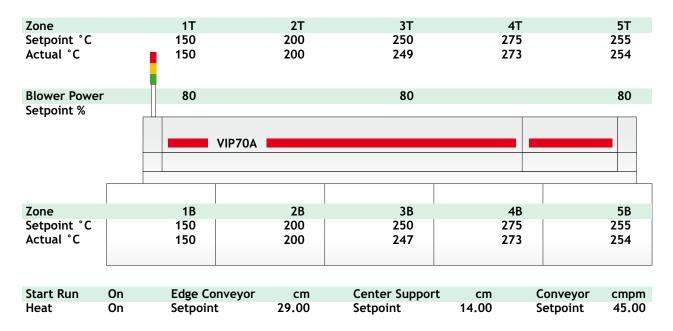
Application requirements

Storage	Printing	Reflow	Cleaning
 store in temp. 3-7°C for no longer than 6 months in tightly closed containers. the best (optimal) temperature of paste application: 23-26°C max. temperature of paste application: 28°C in order to avoid changes in rheology of the paste do not mix used with unused paste. in order to prevent condensation of moisture and to achieve required properties of the paste warm the container up to room temperature for several hours before opening 	 laser-cut stencils or electro-formed stencils: 100µm for pitch = 0.4mm 150µm for pitch > 0.5 mm metal stencils are recommended squeegee travel speed in a printer: 25- 150 mm/sec squeegee pressure: 1.5- 3N at a cm of length amount of paste on a stencil: size of a roll rolling ahead of squeegee is 15-20mm 	 any soldering methods are allowed (air or nitrogen atmospheres) preheating: ramp-up temperature 1-2,0°C/s to 145-160°C or max. 210- 220°C for versions without plateau plateau phase (only for packages with high density assemblies having different mass) 145-160°C for 60- 90s soldering - reflow phase: 30-90s above 180°C cooling: gradient: 1-2°C/s 	 as a rule a no-clean paste does not require cleanin however if cleaning is necessary it is recommended to use alcohol PCB cleaner.

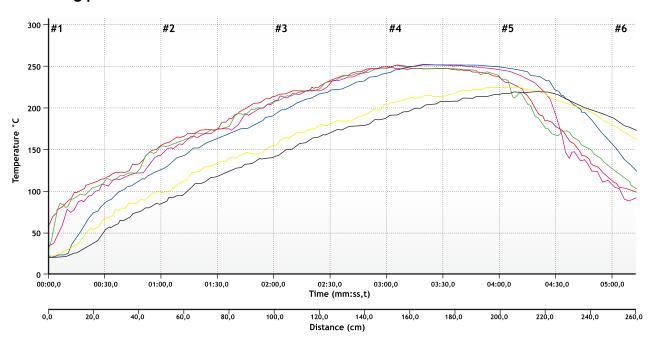




Soldering procedure for profile No. 1



Soldering profile No. 1 used in research



Reflow Results

	Probe	Positive Slope (°C/sec)	Positive Slope Time (mm:ss,t)	Rise Time (150,0 - 190,0 °C) (mm:ss,t)	Time Above Liquidus (217,0°C) (mm:ss,t)	Peak Temperature (°C)	Delta T (°C)	Negative Slope (°C/sec)
ſ	#1 (°C)	4,50	00:00,0	00:43,0	02:08,0	249,0		-3,25
ſ	#2 (°C)	7,20	00:03,0	00:42,0	01:55,0	250,5		-3,14
ſ	#3 (°C)	3,68	00:16,0	00:43,0	02:06,0	252,0	● 32,0	-2,74
ſ	#4 (°C)	2,37	00:28,0	00:53,0	00:29,0	220,0	0	-1,37
-[#5 (°C)	2,36	00:18,0	00:50,0	00:49,0	224,5		-1,49
ſ	#6 (°C)	4,72	00:06,0	00:41,0	02:10,0	252,0	•	-7,61

